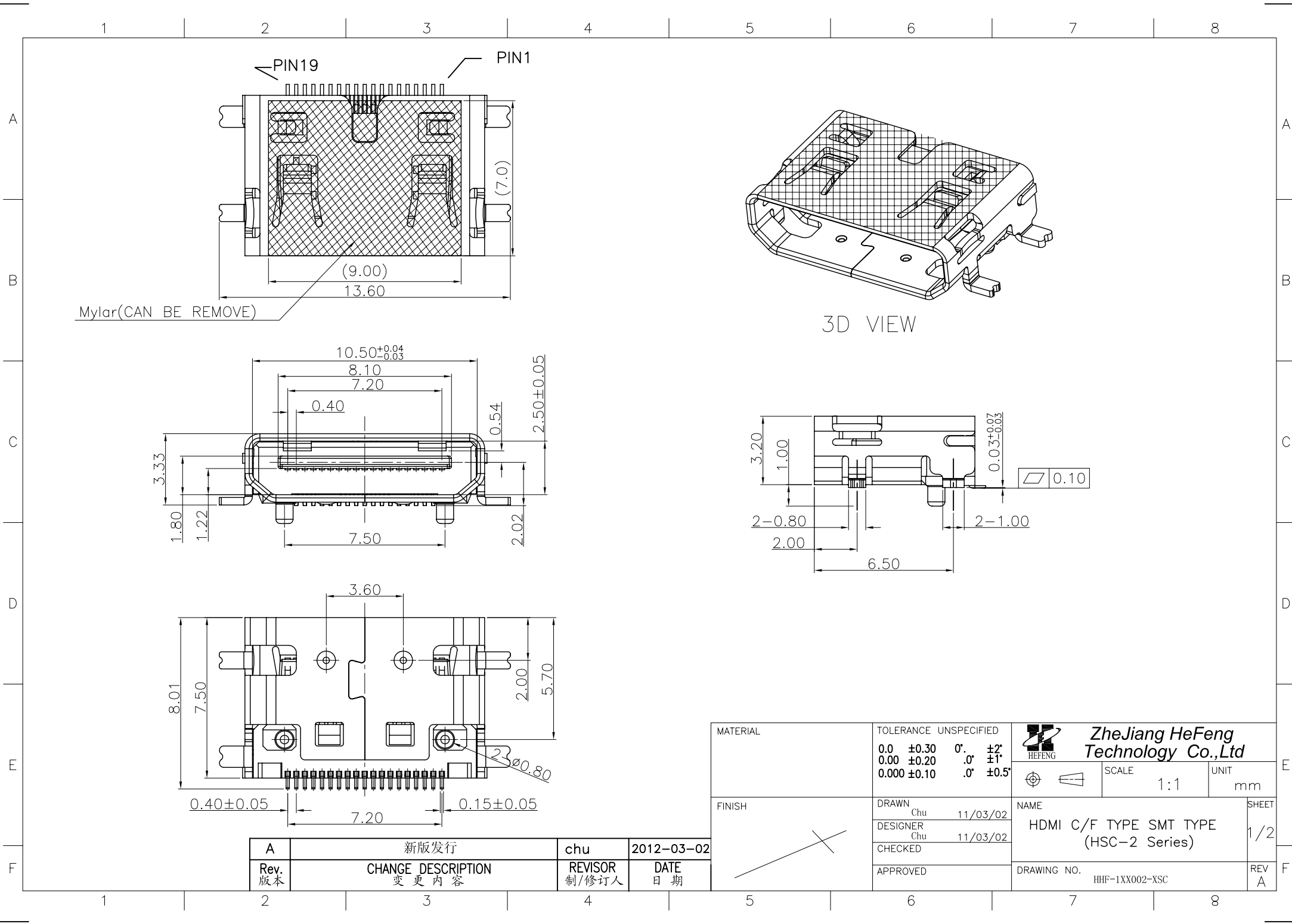
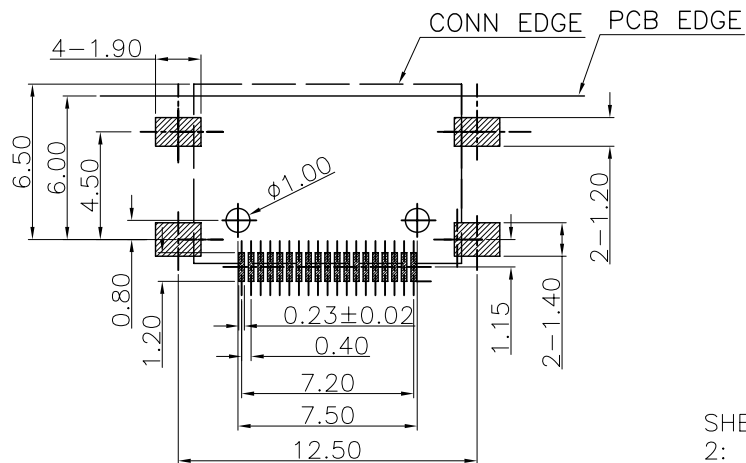






RECOMMENDED PCB LAYOUT(TOP VIEW)
(THICKNESS=0.8±0.05mm)
TOLERANCE = ±0.05

PIN	Signal Name	PIN	Signal Name
1	TMDS DATA2 Shield	11	TMDS Clock+
2	TMDS DATA2+	12	TMDS Clock-
3	TMDS DATA2-	13	DDC/CEC Ground
4	TMDS DATA1 Shield	14	CEC
5	TMDS DATA1+	15	SCL
6	TMDS DATA1-	16	SDA
7	TMDS DATA0 Shield	17	Reserved(in cable but N.C.on device)
8	TMDS DATA0+		
9	TMDS DATA0-	18	+5V Power
10	TMDS Clock Shield	19	Hot Plug Detect

A	新版发行	chu	2012-03-02
Rev. 版本	CHANGE DESCRIPTION 变更内容	REVISOR 制/修订人	DATE 日期

NOTES:

1. MATERIAL:

- 1.1 HOUSING: LCP, BLACK, UL94V-0
- 1.2 SHELL: BRASS
- 1.3 TERMINAL: PHOSPHOR BRONZE
- 1.4 MYLAR:

2. PLATING:

- 1.1 SHELL: GOLD PLATING OVER NICKEL
UNDERPLATED/NICKEL PLATING OVER ALL
- 1.2 TERMINAL: GOLD PLATING ON CONTACT
AREA AND TIN PLATING ON
SOLDER AREA, NICKEL UNDERPLATING OVER ALL

3.All RAW MATERIAL,COMPONENTS,AND PROCESS MUST MEET
HAZARD SUSTAIN FREE PER RoHS & REACH STANDARD.

4. P/N:

HHF-1XX002-XSC

SHELL MATERIAL & PLATING CODE:

- 2: MATERIAL:COPPER ALLOY
NICKEL PLATING WITHOUT FLANGE
- 6: MATERIAL:COPPER ALLOY
GOLD PLATING WITHOUT FLANG

PACKAGING CODE

- 1: TARY PACKING
- 2: TAPE REEL PACKAGEING
- 3: TUBE PACKING

MYLAR:

- 0: WITHOUT MYLAR
- 1: WITH MYLAR

TERMINAL CONTACT

AREA PLATING CODE:

- 1: CONTACT AREA: GOLD FLASH
SOLDER AREA: GOLD FLASH
- 2: CONTACT AREA: 3u" GOLD
SOLDER AREA: GOLD FLASH
- A: CONTACT AREA: GOLD FLASH
SOLDER AREA: MATTE TIN 100u"
- B: CONTACT AREA: 3u" GOLD
SOLDER AREA: MATTE TIN 100u"

MATERIAL	TOLERANCE UNSPECIFIED		 ZheJiang HeFeng Technology Co.,Ltd	SCALE 1:1	UNIT mm
	0.0 ±0.30	0. ±2'			
	0.00 ±0.20	.0' ±1'			
	0.000 ±0.10	.0' ±0.5'			
FINISH	DRAWN	Chu	11/03/02	NAME HDMI C/F TYPE SMT TYPE (HSC-2 Series)	SHEET 2/2
	DESIGNER	Chu	11/03/02		
	CHECKED				
	APPROVED				
				DRAWING NO. HHF-1XX002-XSC	REV A